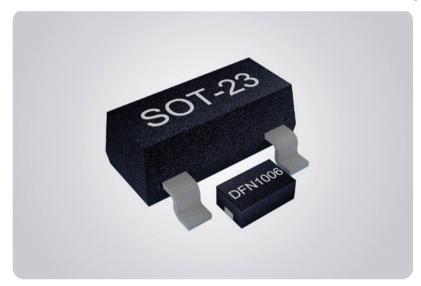




BAS16L, BAS40L

Small Signal 40 V Schottky and 100 V Switching Diodes in Ultra Compact DFN1006-2A Package with Visible and Wettable Side Terminals for Commercial and Automotive Applications



KEY BENEFITS

- Leadless ultra small DFN1006-2A package (1 mm × 0.6 mm × 0.45 mm) with wettable flanks
- Power dissipation better than SOT-23
- Available in an AEC-Q101 qualified versions
- Surface-mounted device (SMD) plastic package with visible and sidewall plated / wettable flanks
- Designed to save space and improve thermal performance
- BAS40L is protected by a PN junction guard ring against excessive voltage, such as electrostatic discharges
- Moisture sensitivity level (MSL) of 1 in accordance with J-STD-020
- UL 94 V-0 flammability rating
- Support automated optical inspection (AOI) for automotive systems
- Soldering can be checked by standard vision inspection; no X-ray is required
- RoHS-compliant, halogen-free, and Vishay Green

APPLICATIONS

Standard switching and Schottky diodes for automotive and industrial applications

RESOURCES

- Datasheets: BAS16L (www.vishay.com/ppg?86187); BAS40L (www.vishay.com/ppg?86189)
- Application note: Soldering Recommendations for DFN Packages (<u>www.vishay.com/doc?86198</u>)
- For technical questions, contact: <u>DiodesAmericas@vishay.com</u>, <u>DiodesEurope@vishay.com</u>, <u>DiodesAsia@vishay.com</u>
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912







RoHS

HALOGEN FREE

<u>GREEN</u> (5-2008)

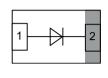




BAS16L. BAS40L

Small Signal 40 V Schottky and 100 V Switching Diodes in Ultra Compact DFN1006-2A Package with Visible and Wettable **Side Terminals for Commercial and Automotive Applications**





LINKS TO ADDITIONAL RESOURCES







MECHANICAL DATA

Case: DFN1006-2A Weight: 0.83 mg

Molding compound flammability rating: UL 94 V-0 Terminals: high temperature soldering guaranteed:

Peak temperature max. 260 °C Packaging codes / options: 08/10K per 7" reel (8 mm tape)

FEATURES

- Silicon epitaxial planar diode
- Fast switching diode
- Leadless ultra small DFN1006-2A package $(1 \text{ mm} \times 0.6 \text{ mm} \times 0.45 \text{ mm})$
- Power dissipation better than SOT-23
- Surface-mounted device (SMD) plastic package with visible and sidewall plated / wettable flanks
- Soldering can be checked by standard visual inspection. No X-ray inspection necessary to meet automotive AOI requirements
- AEC-Q101 qualified available
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912





AUTOMOTIVE





RoHS HALOGEN FREE GREEN (5-2008)

PARTS TABLE AEC-Q101 QUALIFIED CIRCUIT CONFIGURATION TYPE MARKING REMARKS PART **ORDERING CODE** BAS16L-G3-08 BAS16L Single Tape and reel D. BAS16L-HG3-08 ves

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)					
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT	
Reverse voltage		V _R	100	V	
Forward current	on FR-4 board with recommended soldering footprint	I _F	250	mA	
Non repetitive forward current (1)	t _p = 1 μs		9	А	
	t _p = 1 ms	I _{FSM}	1.7		
	t _p = 1 s		0.5		
Repetitive peak forward current	$T_L = 100 ^{\circ}\text{C}, t_p = \le 1 \text{ms}, D = 0.05$	I _{FRM}	500	mA	
Dower dissination	on FR-4 board with recommended soldering footprint	В	300	mW	
Power dissipation	$R_{thJL} = 100 \text{ K/W}$	- P _{tot}	1250	mW	

(1) Square wave, T_i = 25 °C prior to surge

THERMAL CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL VALUE		UNIT		
Thermal resistance junction to ambient air	according to JEDEC® 51-3 on FR-4 board with recommended soldering footprint	R _{thJA}	420	K/W		
Thermal resistance junction to lead		R _{thJL}	100	K/W		
Maximum junction temperature		T _{j max} .	150	°C		
Storage temperature range		T _{stg}	-55 to +150	°C		
Operating temperature range		T _{op}	-55 to +150	°C		

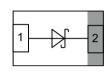




BAS16L, BAS40L

Small Signal 40 V Schottky and 100 V Switching Diodes in Ultra Compact DFN1006-2A Package with Visible and Wettable Side Terminals for Commercial and Automotive Applications





LINKS TO ADDITIONAL RESOURCES







MECHANICAL DATA

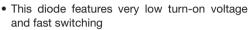
Case: DFN1006-2A Weight: 0.83 mg

Molding compound flammability rating: UL 94 V-0

Terminals: high temperature soldering guaranteed:

Peak temperature max. 260 °C Packaging codes/options: 08/10K per 7" reel (8 mm tape)

FEATURES





 This device is protected by a PN junction guard ring against excessive voltage, such as electrostatic discharges



- Leadless ultra small DFN1006-2A package (1 mm × 0.6 mm × 0.45 mm)
- Power dissipation better than SOT-23
- Surface-mounted device (SMD) plastic package with visible and sidewall plated / wettable flanks



- Soldering can be checked by standard visual inspection. No X-ray inspection necessary to meet automotive AOI requirements
- AEC-Q101 qualified available
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

PARTS TABLE						
PART	ORDERING CODE	AEC-Q101 QUALIFIED	CIRCUIT CONFIGURATION	TYPE MARKING	REMARKS	
BAS40L	BAS40L-G3-08	no	Single	۸	Tape and reel	
DA340L	BAS40L-HG3-08	yes	Single	A.		

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL VALUE		UNIT
Reverse voltage		V_R	40	V
Forward current	on FR-4 board with recommended soldering footprint	I _F	200	mA
Non-repetitive peak forward current	$T_j = 25 ^{\circ}\text{C}, t_p = 10 \text{ms}$		500	mA
	$T_j = 100 ^{\circ}\text{C}, t_p = 10 \text{ms}$	I _{FSM}	200	
	T _j = 125 °C, t _p = 20 μs		500	
Power dissipation	on FR-4 board with recommended soldering footprint	В	300	mW
	R _{thJL} = 100 K/W	P _{tot}	1250	mW

THERMAL CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER			UNIT			
Thermal resistance junction to ambient air	according to JEDEC [®] 51-3 on FR-4 board with recommended soldering footprint	R _{thJA}	420	K/W		
Thermal resistance junction to lead		R _{thJL}	100	K/W		
Maximum junction temperature		T _{j max.}	150	°C		
Storage temperature range		T _{stg}	-55 to +150	°C		
Operating temperature range		T _{op}	-55 to +150	°C		